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Attorney Docket No. 1057

PATENT

22390 U.S. PTO  
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121003

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

The patent application of

Inventor(s): TAKEO KURAMOTO ET AL

For: SOLDER BALL ASSEMBLY FOR BUMP FORMATION AND  
METHOD FOR ITS MANUFACTURE

is attached for filing.

[X] This application is being filed without a declaration or  
fee.

[X] This application claims the priority of Japanese Patent  
Application No. 2002-359405 filed on December 11, 2002.

Respectfully submitted,

Michael Tobias  
Registration Number 32,948

#40  
1717 K Street, N.W., Suite 613  
Washington, D.C. 20036  
Telephone: (301) 587-6541  
Facsimile: (301) 587-6623  
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